

Technical Data Sheet

THICK FILM MATERIALS

Product Type: End Terminations

Product Name: ET2001-1



Polymer Silver Plateable End Termination

Description

ET2001-1 is a dippable polymer based silver end termination. It contains a fast curing polymer system.

ET2001-1 is a Pb and Cd free Ni/Sn plateable polymer end termination designed to be compatible on multilayer ceramic chip capacitors (NPO and X7R bodies).

Key Benefits

- Ni and Sn plateable
- Solvent resistant
- Pb and Cd free

Typical Properties

Metal Type

Silver

Adhesion

Excellent Adhesion

Solvent Resistance

Excellent

Viscosity

20 – 40 Kcps Brookfield HBT

SC4 – 14 spindle, 6R utility cup at 10 rpm, 25 °C

% Solids

73.5 ± 1.5 %

Application

A blotting step can be used to control the amount of paste deposited on the chip body, if needed.

Recommended Processing Guidelines

Mixing

Material should be thoroughly mixed prior to use

Cleaning

Clean uncured resin with Acetone or similar solvent

Drying

120 °C for 20 minutes

Curing

185 °C for 60 minutes

Thinner:

V-521

Warranty:

Material guaranteed to meet specifications for 3 months from date of shipment.

Handling and Precautions:

Use in a well-ventilated area

Avoid contact with skin

Wash with soap and water

Storage:

Refrigeration a 5 °C required to maintain shelf life.

Allow paste to come to room temperature prior to opening.

Spatulate well before using, as settling may occur during storage.

3 months shelf life at room temperature

6 months shelf life when stored in refrigeration

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